

**FM25V05** 

# 512-Kbit (64 K × 8) Serial (SPI) F-RAM

### Features

- 512-Kbit ferroelectric random access memory (F-RAM) logically organized as 64 K × 8
  - □ High-endurance 100 trillion (10<sup>14</sup>) read/writes
  - □ 151-year data retention (See the Data Retention and Endurance table)
  - □ NoDelay<sup>™</sup> writes
  - Advanced high-reliability ferroelectric process
- Very fast serial peripheral interface (SPI)
  - □ Up to 40-MHz frequency
  - Direct hardware replacement for serial flash and EEPROM
  - $\Box$  Supports SPI mode 0 (0, 0) and mode 3 (1, 1)
- Sophisticated write protection scheme Hardware protection using the Write Protect (WP) pin Software protection using Write Disable instruction □ Software block protection for 1/4, 1/2, or entire array
- Device ID Manufacturer ID and Product ID
- Low power consumption 300 μA active current at 1 MHz **90** μA (typ) standby current □ 5 µA sleep mode current
- Low-voltage operation: V<sub>DD</sub> = 2.0 V to 3.6 V
- Industrial temperature: -40 °C to +85 °C
- 8-pin small outline integrated circuit (SOIC) package
- Restriction of hazardous substances (RoHS) compliant

### Functional Description

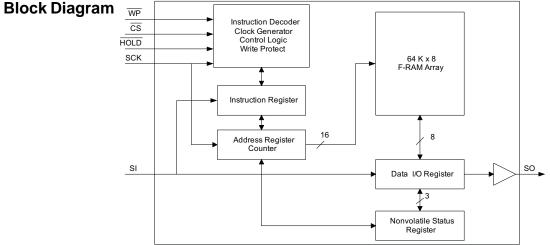
The FM25V05 is a 512-Kbit nonvolatile memory employing an advanced ferroelectric process. A ferroelectric random access memory or F-RAM is nonvolatile and performs reads and writes similar to a RAM. It provides reliable data retention for 151 years while eliminating the complexities, overhead, and system-level reliability problems caused by serial flash, EEPROM, and other nonvolatile memories.

Unlike serial flash and EEPROM, the FM25V05 performs write operations at bus speed. No write delays are incurred. Data is written to the memory array immediately after each byte is successfully transferred to the device. The next bus cycle can commence without the need for data polling. In addition, the product offers substantial write endurance compared with other nonvolatile memories. The FM25V05 is capable of supporting 10<sup>14</sup> read/write cycles, or 100 million times more write cycles than EEPROM.

These capabilities make the FM25V05 ideal for nonvolatile memory applications, requiring frequent or rapid writes. Examples range from data collection, where the number of write cycles may be critical, to demanding industrial controls where the long write time of serial flash or EEPROM can cause data loss.

The FM25V05 provides substantial benefits to users of serial EEPROM or flash as a hardware drop-in replacement. The FM25V05 uses the high-speed SPI bus, which enhances the high-speed write capability of F-RAM technology. The device incorporates a read-only Device ID that allows the host to determine the manufacturer, product density, and product revision. The device specifications are guaranteed over an industrial temperature range of -40 °C to +85 °C.

For a complete list of related documentation, click here.



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### Logic Block Diagram



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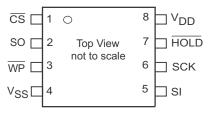
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### Pinouts

#### Figure 1. 8-pin SOIC pinout



### **Pin Definitions**

Pin Name	I/O Type	Description
CS	Input	<b>Chip Select</b> . This active LOW input activates the device. When HIGH, the device enters low-power standby mode, ignores other inputs, and the output is tristated. When LOW, the device internally activates the SCK signal. A falling edge on CS must occur before every opcode.
SCK	Input	Serial Clock. All I/O activity is synchronized to the serial clock. Inputs are latched on the rising edge and outputs occur on the falling edge. Because the device is synchronous, the clock frequency may be any value between 0 and 40 MHz and may be interrupted at any time.
SI <sup>[1]</sup>	Input	Serial Input. All data is input to the device on this pin. The pin is sampled on the rising edge of SCK and is ignored at other times. It should always be driven to a valid logic level to meet IDD specifications.
SO <sup>[1]</sup>	Output	Serial Output. This is the data output pin. It is driven during a read and remains tristated at all other times including when HOLD is LOW. Data transitions are driven on the falling edge of the serial clock.
WP	Input	<b>Write Protect</b> . This Active LOW pin prevents write operation to the Status Register when WPEN is set to '1'. This is critical because other write protection features are controlled through the Status Register. A complete explanation of write protection is provided in Status Register and Write Protection on page 7. This pin must be tied to $V_{DD}$ if not used.
HOLD	Input	<b>HOLD Pin</b> . The HOLD pin is used when the host CPU must interrupt a memory operation for another task. When HOLD is LOW, the current operation is suspended. The device ignores any transition on SCK or CS. All transitions on HOLD must occur while SCK is LOW. This pin has a weak internal pull-up (Refer DC Electrical Characteristics table for R <sub>IN</sub> spec). However, if it is not used, the HOLD pin should be tied to V <sub>DD</sub> .
V <sub>SS</sub>	Power supply	Ground for the device. Must be connected to the ground of the system.
V <sub>DD</sub>	Power supply	Power supply input to the device.

<sup>1.</sup> SI may be connected to SO for a single pin data interface.



### **Functional Overview**

The FM25V05 is a serial F-RAM memory. The memory array is logically organized as  $65,536 \times 8$  bits and is accessed using an industry-standard serial peripheral interface (SPI) bus. The functional operation of the F-RAM is similar to serial flash and serial EEPROMs. The major difference between the FM25V05 and a serial flash or EEPROM with the same pinout is the F-RAM's superior write performance, high endurance, and low power consumption.

#### **Memory Architecture**

When accessing the FM25V05, the user addresses 64K locations of eight data bits each. These eight data bits are shifted in or out serially. The addresses are accessed using the SPI protocol, which includes a chip select (to permit multiple devices on the bus), an opcode, and a two-byte address. The complete address of 16 bits specifies each byte address uniquely.

Most functions of the FM25V05 are either controlled by the SPI interface or handled by on-board circuitry. The access time for the memory operation is essentially zero, beyond the time needed for the serial protocol. That is, the memory is read or written at the speed of the SPI bus. Unlike a serial flash or EEPROM, it is not necessary to poll the device for a ready condition because writes occur at bus speed. By the time a new bus transaction can be shifted into the device, a write operation is complete. This is explained in more detail in the interface section.

#### Serial Peripheral Interface – SPI Bus

The FM25V05 is a SPI slave device and operates at speeds up to 40 MHz. This high-speed serial bus provides high-performance serial communication to a SPI master. Many common microcontrollers have hardware SPI ports allowing a direct interface. It is quite simple to emulate the port using ordinary port pins for microcontrollers that do not. The FM25V05 operates in SPI Mode 0 and 3.

#### **SPI** Overview

The SPI is a four-pin interface with Chip Select ( $\overline{CS}$ ), Serial Input (SI), Serial Output (SO), and Serial Clock (SCK) pins.

The SPI is a synchronous serial interface, which uses clock and data pins for memory access and supports multiple devices on the data bus. A device on the SPI bus is activated using the CS pin.

The relationship between chip select, clock, and data is dictated by the SPI mode. This device supports SPI modes 0 and 3. In both of these modes, data is clocked into the F-RAM on the rising edge of SCK starting from the first rising edge after  $\overline{CS}$  goes active.

The SPI protocol is controlled by opcodes. These opcodes specify the commands from the bus master to the slave device. After  $\overline{CS}$  is activated, the first byte transferred from the bus master is the opcode. Following the opcode, any addresses and data are then transferred. The  $\overline{CS}$  must go inactive after an

operation is complete and before a new opcode can be issued. The commonly used terms in the SPI protocol are as follows:

#### SPI Master

The SPI master device controls the operations on a SPI bus. An SPI bus may have only one master with one or more slave devices. All the slaves share the same SPI bus lines and the master may select any of the slave devices using the  $\overline{CS}$  pin. All of the operations must be initiated by the master activating a slave device by pulling the  $\overline{CS}$  pin of the slave LOW. The master also generates the SCK and all the data transmission on SI and SO lines are synchronized with this clock.

#### SPI Slave

The SPI slave device is activated by the master through the Chip Select line. A slave device gets the SCK as an input from the SPI master and all the communication is synchronized with this clock. An SPI slave never initiates a communication on the SPI bus and acts only on the instruction from the master.

The FM25V05 operates as an SPI slave and may share the SPI bus with other SPI slave devices.

#### Chip Select (CS)

To select any slave device, the master needs to pull down the corresponding  $\overline{CS}$  pin. Any instruction can be issued to a slave device only while the  $\overline{CS}$  pin is LOW. When the device is not selected, data through the SI pin is ignored and the serial output pin (SO) remains in a high-impedance state.

**Note** A new instruction must begin with the falling edge of  $\overline{CS}$ . Therefore, only one opcode can be issued for each active Chip Select cycle.

#### Serial Clock (SCK)

The Serial Clock is generated by the SPI master and the communication is synchronized with this clock after  $\overline{\text{CS}}$  goes LOW.

The FM25V05 enables SPI modes 0 and 3 for data communication. In both of these modes, the inputs are latched by the slave device on the rising edge of SCK and outputs are issued on the falling edge. Therefore, the first rising edge of SCK signifies the arrival of the first bit (MSB) of a SPI instruction on the SI pin. Further, all data inputs and outputs are synchronized with SCK.

#### Data Transmission (SI/SO)

The SPI data bus consists of two lines, SI and SO, for serial data communication. SI is also referred to as Master Out Slave In (MOSI) and SO is referred to as Master In Slave Out (MISO). The master issues instructions to the slave through the SI pin, while the slave responds through the SO pin. Multiple slave devices may share the SI and SO lines as described earlier.

The FM25V05 has two separate pins for SI and SO, which can be connected with the master as shown in Figure 2.

For a microcontroller that has no dedicated SPI bus, a general-purpose port may be used. To reduce hardware



resources on the controller, it is possible to connect the two data pins (SI, SO) together and tie off (HIGH) the  $\overline{HOLD}$  and  $\overline{WP}$  pins. Figure 3 shows such a configuration, which uses only three pins.

#### Most Significant Bit (MSB)

The SPI protocol requires that the first bit to be transmitted is the Most Significant Bit (MSB). This is valid for both address and data transmission.

The 512-Kbit serial F-RAM requires a 2-byte address for any read or write operation.

#### Serial Opcode

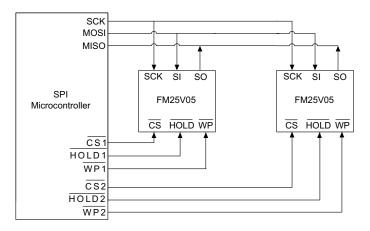
After the slave device is selected with  $\overline{CS}$  going LOW, the first byte received is treated as the opcode for the intended operation. FM25V05 uses the standard opcodes for memory accesses.

#### Invalid Opcode

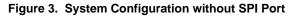
If an invalid opcode is received, the opcode is ignored and the device ignores any <u>additional</u> serial data on the SI pin until the next falling edge of CS, and the SO pin remains tristated.

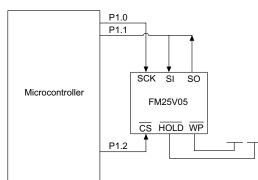
#### Status Register

FM25V05 has an 8-bit Status Register. The bits in the Status Register are used to configure the device. These bits are described in Table 3 on page 7.



#### Figure 2. System Configuration with SPI Port





#### **SPI Modes**

FM25V05 may be driven by a microcontroller with its SPI peripheral running in either of the following two modes:

- SPI Mode 0 (CPOL = 0, CPHA = 0)
- SPI Mode 3 (CPOL = 1, CPHA = 1)

For both these modes, the input data is latched in on the rising edge of SCK starting from the first rising edge after  $\overline{CS}$  goes

active. If the clock starts from a HIGH state (in mode 3), the first rising edge after the clock toggles is considered. The output data is available on the falling edge of SCK.

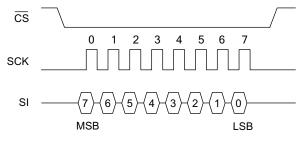
The two SPI modes are shown in Figure 4 on page 6 and Figure 5 on page 6. The status of the clock when the bus master is not transferring data is:

- SCK remains at 0 for Mode 0
- SCK remains at 1 for Mode 3

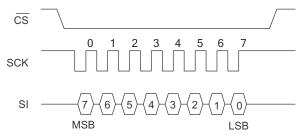


The device detects the SPI mode from the status of the SCK pin when the device is selected by bringing the  $\overline{CS}$  pin LOW. If the SCK pin is LOW when the device is selected, SPI Mode 0 is assumed and if the SCK pin is HIGH, it works in SPI Mode 3.

#### Figure 4. SPI Mode 0



#### Figure 5. SPI Mode 3



#### Power Up to First Access

The FM25V05 is not accessible for a  $t_{PU}$  time after power-up. Users must comply with the timing parameter,  $t_{PU}$ , which is the minimum time from  $V_{DD}$  (min) to the first  $\overline{CS}$  LOW.

#### **Command Structure**

There are nine commands, called opcodes, that can be issued by the bus master to the FM25V05. They are listed in Table 1. These opcodes control the functions performed by the memory.

#### Table 1. Opcode Commands

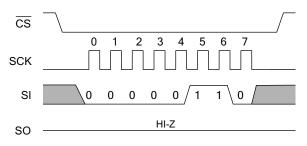
Name	Description	Opcode
WREN	Set write enable latch	0000 0110b
WRDI	Reset write enable latch	0000 0100b
RDSR	Read Status Register	0000 0101b
WRSR	Write Status Register	0000 0001b
READ	Read memory data	0000 0011b
FSTRD	Fast read memory data	0000 1011b
WRITE	Write memory data	0000 0010b
SLEEP	Enter sleep mode	1011 1001b
RDID	Read device ID	1001 1111b

#### WREN - Set Write Enable Latch

The FM25V05 will power up with writes disabled. The WREN command must be issued before any write operation. Sending the WREN opcode allows the user to issue subsequent opcodes for write operations. These include writing the Status Register (WRSR) and writing the memory (WRITE).

Sending the WREN opcode causes the internal Write Enable Latch to be set. A flag bit in the Status Register, called WEL, indicates the state of the latch. WEL = '1' indicates that writes are permitted. Attempting to write the WEL bit in the Status Register has no effect on the state of this bit – only the WREN opcode can set this bit. The WEL bit will be automatically cleared on the rising edge of  $\overline{CS}$  following a WRDI, a WRSR, or a WRITE operation. This prevents further writes to the Status Register or the F-RAM array without another WREN command. Figure 6 illustrates the WREN command bus configuration.

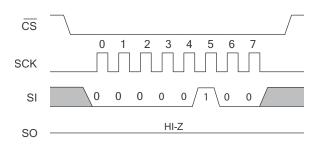
#### Figure 6. WREN Bus Configuration



#### WRDI - Reset Write Enable Latch

The WRDI command disables all write activity by clearing the Write Enable Latch. The user can verify that writes are disabled by reading the WEL bit in the Status Register and verifying that WEL is equal to '0'. Figure 7 illustrates the WRDI command bus configuration.

#### Figure 7. WRDI Bus Configuration





### **Status Register and Write Protection**

The write protection features of the FM25V05 are multi-tiered and are enabled through the status register. The Status Register

is organized as follows. (The default value shipped from the factory for bit 0, WEL, BP0, BP1, bits 4–5, WPEN is '0', and for bit 6 is '1').

#### Table 2. Status Register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
WPEN (0)	X (1)	X (0)	X (0)	BP1 (0)	BP0 (0)	WEL (0)	X (0)

#### Table 3. Status Register Bit Definition

Bit	Definition	Description		
Bit 0	Don't care	This bit is non-writable and always returns '0' upon read.		
Bit 1 (WEL)	Write Enable	WEL indicates if the device is write enabled. This bit defaults to '0' (disabled) on power WEL = '1'> Write enabled WEL = '0'> Write disabled		
Bit 2 (BP0)	Block Protect bit '0'	Used for block protection. For details, see Table 4 on page 7.		
Bit 3 (BP1)	Block Protect bit '1'	Used for block protection. For details, see Table 4 on page 7.		
Bit 4-5	Don't care	These bits are non-writable and always return '0' upon read.		
Bit 6	Don't care	This bit is non-writable and always return '1' upon read.		
Bit 7 (WPEN)	Write Protect Enable bit	Used to enable the function of Write Protect Pin ( $\overline{WP}$ ). For details, see Table 5 on page 7.		

Bits 0 and 4-5 are fixed at '0' and bit 6 is fixed at '1'; none of these bits can be modified. Note that bit 0 ("Ready or Write in progress" bit in serial flash and EEPROM) is unnecessary, as the F-RAM writes in real-time and is never busy, so it reads out as a '0'. An exception to this is when the device is waking up from sleep mode, which is described in Sleep Mode on page 11. The BP1 and BP0 control the software write-protection features and are nonvolatile bits. The WEL flag indicates the state of the Write Enable Latch. Attempting to directly write the WEL bit in the Status Register has no effect on its state. This bit is internally set and cleared via the WREN and WRDI commands, respectively.

BP1 and BP0 are memory block write protection bits. They specify portions of memory that are write-protected as shown in Table 4.

Table 4.	Block	Memory	Write	Protection
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BP1	BP0	Protected Address Range	
0	0	None	
0	1	C000h to FFFFh (upper 1/4)	
1	0	8000h to FFFFh (upper 1/2)	
1	1	0000h to FFFFh (all)	

The BP1 and BP0 bits and the Write Enable Latch are the only mechanisms that protect the memory from writes. The remaining write protection features protect inadvertent changes to the block protect bits.

The write protect enable bit (WPEN) in the Status Register controls the effect of the hardware write protect ( $\overline{WP}$ ) pin. When the WPEN bit is set to '0', the status of the  $\overline{WP}$  pin is ignored. When the WPEN bit is set to '1', a LOW on the WP pin inhibits a write to the Status Register. Thus the Status Register is write-protected only when WPEN = '1' and  $\overline{WP}$  = '0'.

Table 5 summarizes the write protection conditions.

Table 5	5. Write	Protection
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WEL	WPEN	WP	Protected Blocks	Unprotected Blocks	Status Register
0	Х	Х	Protected	Protected	Protected
1	0	Х	Protected	Unprotected	Unprotected
1	1	0	Protected	Unprotected	Protected
1	1	1	Protected	Unprotected	Unprotected



#### **RDSR - Read Status Register**

The RDSR command allows the bus master to verify the contents of the Status Register. Reading the status register provides information about the current state of the write-protection features. Following the RDSR opcode, the FM25V05 will return one byte with the contents of the Status Register.

setting the WPEN, BP0 and BP1 bits as required. Before issuing a WRSR command, the WP pin must be HIGH or inactive. Note that on the FM25V05, WP only prevents writing to the Status Register, not the memory array. Before sending the WRSR command, the user must send a WREN command to enable writes. Executing a WRSR command is a write operation and therefore, clears the Write Enable Latch.

#### WRSR - Write Status Register

The WRSR command allows the SPI bus master to write into the Status Register and change the write protect configuration by

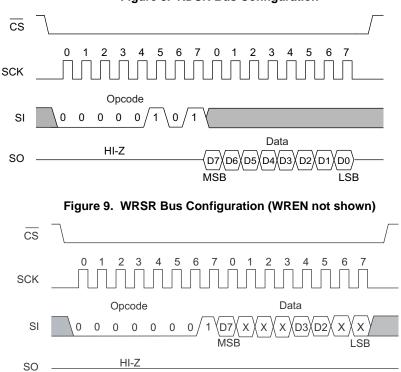


Figure 8. RDSR Bus Configuration

#### **Memory Operation**

The SPI interface, which is capable of a high clock frequency, highlights the fast write capability of the F-RAM technology. Unlike serial flash and EEPROMs, the FM25V05 can perform sequential writes at bus speed. No page register is needed and any number of sequential writes may be performed.

#### Write Operation

All writes to the memory begin with a WREN opcode with  $\overline{CS}$  being asserted and deasserted. The next opcode is WRITE. The WRITE opcode is followed by a two-byte address containing the 16-bit address (A15-A0) of the first data byte to be written into the memory. Subsequent bytes are data bytes, which are written sequentially. Addresses are incremented internally as long as the bus master continues to issue clocks and keeps  $\overline{CS}$  LOW. If

the last address of FFFFh is reached, the counter will roll over to 0000h. Data is written MSB first. The rising edge of  $\overline{CS}$  terminates a write operation. A write operation is shown in Figure 10.

**Note** When a burst write reaches a protected block address, the automatic address increment stops and all the subsequent data bytes received for write will be ignored by the device.

EEPROMs use page buffers to increase their write throughput. This compensates for the technology's inherently slow write operations. F-RAM memories do not have page buffers because each byte is written to the F-RAM array immediately after it is clocked in (after the eighth clock). This allows any number of bytes to be written without page buffer delays.

**Note** If the power is lost in the middle of the write operation, only the last completed byte will be written.

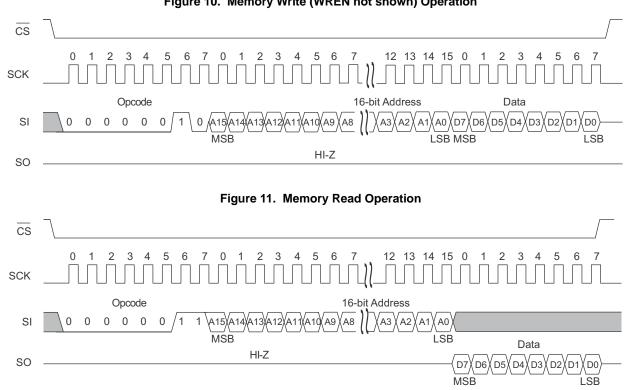


#### Read Operation

After the falling edge of  $\overline{CS}$ , the bus master can issue a READ opcode. Following the READ command is a two-byte address containing the 16-bit address (A15-A0) of the first byte of the read operation. After the opcode and address are issued, the device drives out the read data on the next eight clocks. The SI input is ignored during read data bytes. Subsequent bytes are data bytes, which are read out sequentially. Addresses are incremented internally as long as the bus master continues to issue clocks and  $\overline{CS}$  is LOW. If the last address of FFFFh is reached, the counter will roll over to 0000h. Data is read MSB first. The rising edge of CS terminates a read operation and tristates the SO pin. A read operation is shown in Figure 11.

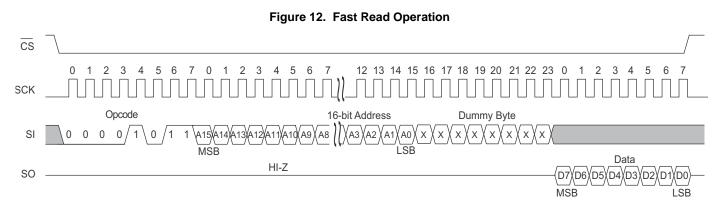
#### **Fast Read Operation**

The FM25V05 supports a FAST READ opcode (0Bh) that is provided for code compatibility with serial flash devices. The FAST READ opcode is followed by a two-byte address containing the 16-bit address (A15-A0) of the first byte of the read operation and then a dummy byte. The dummy byte inserts a read latency of 8-clock cycle. The fast read operation is otherwise the same as an ordinary read operation except that it requires an additional dummy byte. After receiving opcode, address, and a dummy byte, the FM25V05 starts driving its SO line with data bytes, with MSB first, and continues transmitting as long as the device is selected and the clock is available. In case of bulk read, the internal address counter is incremented automatically, and after the last address FFFFh is reached, the counter rolls over to 0000h. When the device is driving data on its SO line, any transition on its SI line is ignored. The rising edge of  $\overline{CS}$  terminates a fast read operation and tristates the SO pin. A Fast Read operation is shown in Figure 12.



#### Figure 10. Memory Write (WREN not shown) Operation

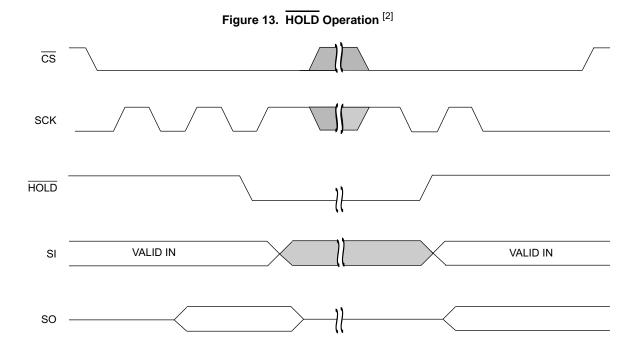




### HOLD Pin Operation

The  $\overline{\text{HOLD}}$  pin can be used to interrupt a serial operation without aborting it. If the bus master pulls the  $\overline{\text{HOLD}}$  pin LOW while SCK is LOW, the current operation will pause. Taking the  $\overline{\text{HOLD}}$  pin

HIGH while <u>SCK</u> is LOW will resume an operation. The transitions of HOLD must occur while SCK is LOW, but the SCK and  $\overline{CS}$  pin can toggle during a hold state.



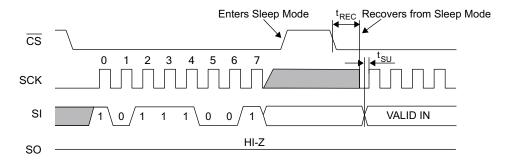


#### **Sleep Mode**

A low-power sleep mode is implemented on the FM25V05 device. The device will enter the low-power state when the SLEEP opcode B9h is clocked in and a rising edge of  $\overline{CS}$  is applied. When in sleep mode, the SCK and SI pins are ignored and SO will be HI-Z, but the device continues to monitor the  $\overline{CS}$ 

pin. On the next falling edge of  $\overline{\text{CS}}$ , the device will return to normal operation within  $t_{\text{REC}}$  time. The SO pin remains in a HI-Z state during the wakeup period. The device does not necessarily respond to an opcode within the wakeup period. To start the wakeup procedure, the controller may send a "dummy" read, for example, and wait the remaining  $t_{\text{REC}}$  time.

#### Figure 14. Sleep Mode Operation



#### **Device ID**

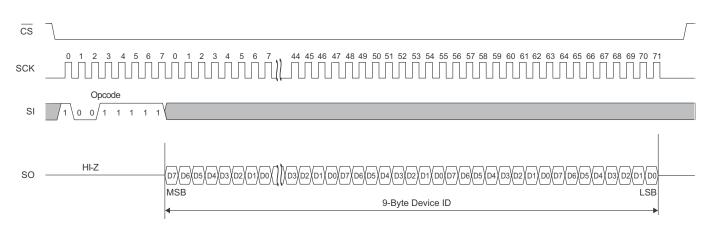
The FM25V05 device can be interrogated for its manufacturer, product identification, and die revision. The RDID opcode 9Fh allows the user to read the manufacturer ID and product ID, both of which are read-only bytes. The JEDEC-assigned

manufacturer ID places the Cypress (Ramtron) identifier in bank 7; therefore, there are six bytes of the continuation code 7Fh followed by the single byte C2h. There are two bytes of product ID, which includes a family code, a density code, a sub code, and the product revision code.

#### Table 6. Device ID

	Device ID Description					
Device ID (9 bytes)	71–16 (56 bits)	15–13 (3 bits)	12–8 (5 bits)	7–6 (2 bits)	5–3 (3 bits)	2–0 (3 bits)
(5 bytes)	Manufacturer ID			Product ID		
		Family	Density	Sub	Rev	Rsvd
7F7F7F7F7F7F7C22300h	011111110111111011111110111 111101111111	001	00011	00	000	000

#### Figure 15. Read Device ID





#### Endurance

The FM25V05 devices are capable of being accessed at least 10<sup>14</sup> times, reads or writes. An F-RAM memory operates with a read and restore mechanism. Therefore, an endurance cycle is applied on a row basis for each access (read or write) to the memory array. The F-RAM architecture is based on an array of rows and columns of 8K rows of 64-bits each. The entire row is internally accessed once, whether a single byte or all eight bytes are read or written. Each byte in the row is counted only once in an endurance calculation. Table 7 shows endurance calculations for a 64-byte repeating loop, which includes an opcode, a starting address, and a sequential 64-byte data stream. This causes each byte to experience one endurance cycle through the loop.

F-RAM read and write endurance is virtually unlimited even at a 40-MHz clock rate.

# Table 7. Time to Reach Endurance Limit for Repeating64-byte Loop

SCK Freq (MHz)	Endurance Cycles/sec	Endurance Cycles/year	Years to Reach Limit
40	74,620	2.35 × 10 <sup>12</sup>	42.6
25	37,310	1.18 × 10 <sup>12</sup>	85.1
10	18,660	5.88 × 10 <sup>11</sup>	170.2
5	9,330	2.94 × 10 <sup>11</sup>	340.3



### **Maximum Ratings**

Exceeding maximum ratings may shorten the useful life of the device. These user guidelines are not tested.

Storage temperature55 °C to +125 °C
Maximum accumulated storage time At 125 °C ambient temperature 1000 h At 85 °C ambient temperature
Ambient temperature with power applied55 °C to +125 °C
Supply voltage on $V_{DD}$ relative to $V_{SS}$ 1.0 V to +4.5 V
Input voltage
DC voltage applied to outputs in High-Z state0.5 V to $V_{\text{DD}}$ + 0.5 V
Transient voltage (< 20 ns) on any pin to ground potential2.0 V to $V_{DD}$ + 2.0 V

Package power dissipation capability ( $T_A = 25 \text{ °C}$ )1.0 W
Surface mount lead soldering temperature (3 seconds)+260 °C
DC output current (1 output at a time, 1s duration)15 mA
Electrostatic Discharge Voltage Human Body Model (AEC-Q100-002 Rev. E)
Charged Device Model (AEC-Q100-011 Rev. B) 1.25 kV
Machine Model (AEC-Q100-003 Rev. E)
Latch-up current> 140 mA

### **Operating Range**

Range	Ambient Temperature (T <sub>A</sub> )	V <sub>DD</sub>
Industrial	–40 °C to +85 °C	2.0 V to 3.6 V

### **DC Electrical Characteristics**

Over the Operating Range

Parameter	Description	Test Conditions	Min	<b>Typ</b> <sup>[3]</sup>	Max	Unit
V <sub>DD</sub>	Power supply		2.0	3.3	3.6	V
I <sub>DD</sub>	V <sub>DD</sub> supply current	SCK toggling f <sub>SCK</sub> = 1 MHz	-	_	0.3	mA
		between $V_{DD} - 0.2 \text{ V}$ and $V_{SS}$ , other inputs $V_{SS}$ or $V_{DD} - 0.2 \text{ V}$ . SO = Open	_	1.5	3.0	mA
I <sub>SB</sub>	V <sub>DD</sub> standby current	$\overline{\text{CS}}$ = V <sub>DD</sub> . All other inputs V <sub>SS</sub> or V <sub>DD</sub> .	-	90	150	μΑ
I <sub>ZZ</sub>	Sleep mode current	$\overline{CS} = V_{DD}.$ All other inputs $V_{SS}$ or $V_{DD}$ .	_	5	8	μΑ
ILI	Input leakage current (except HOLD pin)	$V_{SS} \leq V_{IN} \leq V_{DD}$	Ι	-	±1	μΑ
I <sub>LO</sub>	Output leakage current	$V_{SS} \leq V_{OUT} \leq V_{DD}$	-	_	±1	μΑ
V <sub>IH</sub>	Input HIGH voltage		$0.7 \times V_{DD}$	-	V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input LOW voltage		- 0.3	_	$0.3 \times V_{DD}$	V
V <sub>OH1</sub>	Output HIGH voltage	I <sub>OH</sub> = -1 mA, V <sub>DD</sub> = 2.7 V.	2.4	_	-	V
V <sub>OH2</sub>	Output HIGH voltage	I <sub>OH</sub> = -100 μA	V <sub>DD</sub> – 0.2	_	-	V
V <sub>OL1</sub>	Output LOW voltage	$I_{OL} = 2 \text{ mA}, V_{DD} = 2.7 \text{ V}$	_	_	0.4	V
V <sub>OL2</sub>	Output LOW voltage	I <sub>OL</sub> = 150 μA	_	-	0.2	V
R <sub>IN</sub> <sup>[4]</sup>	Input resistance (HOLD pin)	For V <sub>IN</sub> = V <sub>IH</sub> (min)	40	_	-	kΩ
		For $V_{IN} = V_{IL}(max)$	1	-	-	MΩ

Note
3. Typical values are at 25 °C, V<sub>DD</sub> = V<sub>DD</sub>(typ). Not 100% tested.
4. The input pull-up circuit is strong (> 40 kΩ) when the input voltage is above V<sub>IH</sub> and weak (>1 MΩ) when the input voltage is below V<sub>IL</sub>.



### **Data Retention and Endurance**

Parameter	Description	Test condition	Min	Max	Unit
T <sub>DR</sub>	Data retention	T <sub>A</sub> = 85 °C	10	_	Years
		T <sub>A</sub> = 75 °C	38	_	
		$T_A = 65 \ ^{\circ}C$	151	_	
NV <sub>C</sub>	Endurance	Over operating temperature	10 <sup>14</sup>	_	Cycles

### Capacitance

Parameter <sup>[5]</sup>	Description	Test Conditions	Max	Unit
C <sub>O</sub>	Output pin capacitance (SO)	$T_A = 25 \text{ °C}, f = 1 \text{ MHz}, V_{DD} = V_{DD}(typ)$	8	pF
Cl	Input pin capacitance		6	pF

### **Thermal Resistance**

Parameter	Parameter Description Test Conditions		8-pin SOIC	Unit
$\Theta_{JA}$	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal		°C/W
$\Theta_{JC}$	Thermal resistance (junction to case)	impedance, per EIA / JESD51.	40	°C/W

### **AC Test Conditions**

Input pulse levels	10% and 90% of V <sub>DD</sub>
Input rise and fall times	3 ns
Input and output timing reference leve	els0.5 × V <sub>DD</sub>
Output load capacitance	30 pF

Note5. This parameter is characterized and not 100% tested.



### **AC Switching Characteristics**

#### Over the Operating Range

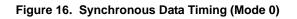
Parameters <sup>[6]</sup>			$V_{DD}$ = 2.0 V to 2.7 V		V <sub>DD</sub> = 2.7 V to 3.6 V		
Cypress Parameter	Alt. Parameter	Description	Min	Мах	Min	Max	Unit
f <sub>SCK</sub>	-	SCK clock frequency	0	25	0	40	MHz
t <sub>CH</sub>	-	Clock HIGH time	20	-	11	-	ns
t <sub>CL</sub>	-	Clock LOW time	20	-	11	-	ns
t <sub>CSU</sub>	t <sub>CSS</sub>	Chip select setup	12	-	10	-	ns
t <sub>CSH</sub>	t <sub>CSH</sub>	Chip select hold	12	-	10	-	ns
t <sub>OD</sub> <sup>[7, 8]</sup>	t <sub>HZCS</sub>	Output disable time	-	20	_	12	ns
t <sub>ODV</sub>	t <sub>CO</sub>	Output data valid time	-	18	-	9	ns
t <sub>OH</sub>	_	Output hold time	0	_	0	_	ns
t <sub>D</sub>	-	Deselect time	60	-	40	-	ns
t <sub>R</sub> <sup>[9, 10]</sup>	-	Data in rise time	_	50	_	50	ns
t <sub>F</sub> <sup>[9, 10]</sup>	-	Data in fall time	_	50	_	50	ns
t <sub>SU</sub>	t <sub>SD</sub>	Data setup time	8	_	5	_	ns
t <sub>H</sub>	t <sub>HD</sub>	Data hold time	8	_	5	_	ns
t <sub>HS</sub>	t <sub>SH</sub>	HOLD setup time	12	_	10	_	ns
t <sub>HH</sub>	t <sub>HH</sub>	HOLD hold time	12	_	10	_	ns
t <sub>HZ</sub> [7, 8]	t <sub>HHZ</sub>	HOLD LOW to HI-Z	_	25	_	20	ns
t <sub>LZ</sub> <sup>[8]</sup>	t <sub>HLZ</sub>	HOLD HIGH to data active	_	25	_	20	ns

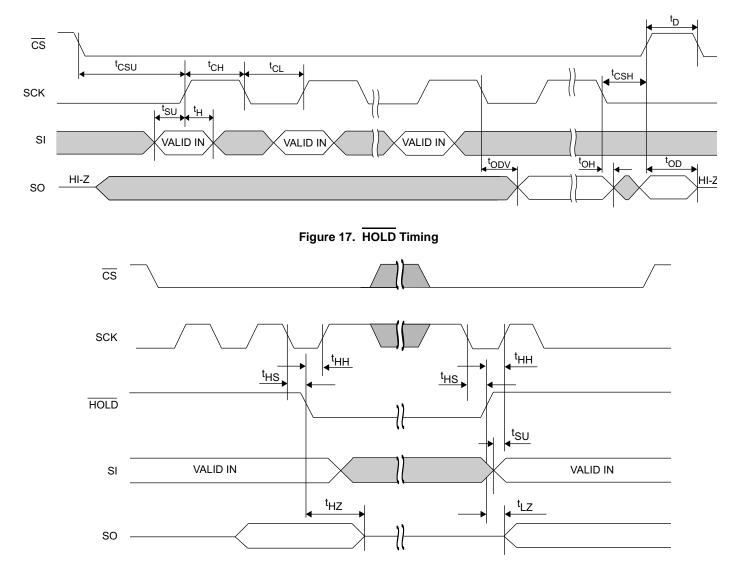
Notes

- 6. Test conditions assume a signal transition time of 3 ns or less, timing reference levels of 0.5 x  $V_{DD}$ , input pulse levels of 10% to 90% of  $V_{DD}$ , and output loading of the specified  $I_{OL}/I_{OH}$  and 30 pF load capacitance shown in AC Test Conditions on page 14. 7.  $t_{OD}$  and  $t_{HZ}$  are specified with a load capacitance of 5 pF. Transition is measured when the outputs enter a high impedance state
- 8. This parameter is characterized and not 100% tested.
- 9. Rise and fall times measured between 10% and 90% of waveform.



FM25V05





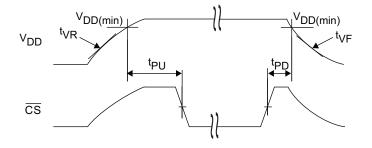


### **Power Cycle Timing**

#### Over the Operating Range

Parameter	Description		Max	Unit
t <sub>PU</sub>	Power-up V <sub>DD</sub> (min) to first access (CS LOW)	250	-	μs
t <sub>PD</sub>	Last access (CS HIGH) to power-down (V <sub>DD</sub> (min))	0	-	μs
t <sub>VR</sub> <sup>[11, 12]</sup>	V <sub>DD</sub> power-up ramp rate		-	µs/V
t <sub>VF</sub> <sup>[11, 12]</sup> V <sub>DD</sub> power-down ramp rate		100	-	µs/V
t <sub>REC</sub> <sup>[13]</sup>	Recovery time from sleep mode	_	400	μs

#### Figure 18. Power Cycle Timing



Notes 11. Slope measured at any point on the  $\rm V_{\rm DD}$  waveform.

12. This parameter is characterized and not 100% tested.

13. Guaranteed by design. Refer to Figure 14 for sleep mode recovery timing.

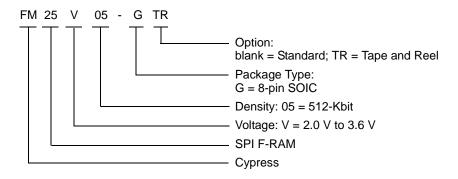


### **Ordering Information**

Ordering Code	Package Diagram	Package Type	Operating Range
FM25V05-G	51-85066	8-pin SOIC	Industrial
FM25V05-GTR	51-85066	8-pin SOIC	

All these parts are Pb-free. Contact your local Cypress sales representative for availability of these parts.

#### **Ordering Code Definitions**



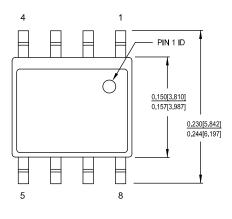


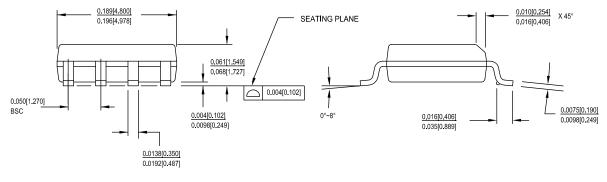
### Package Diagram

#### Figure 19. 8-pin SOIC (150 Mils) Package Outline, 51-85066

- 1. DIMENSIONS IN INCHES[MM] MIN. MAX.
- 2. PIN 1 ID IS OPTIONAL, ROUND ON SINGLE LEADFRAME RECTANGULAR ON MATRIX LEADFRAME
- 3. REFERENCE JEDEC MS-012
- 4. PACKAGE WEIGHT 0.07gms

PART #			
S08.15	STANDARD PKG		
SZ08.15	LEAD FREE PKG		
SW8.15	LEAD FREE PKG		





51-85066 \*H



### Acronyms

Acronym	Description		
CPHA	Clock Phase		
CPOL	Clock Polarity		
EEPROM	Electrically Erasable Programmable Read-Only Memory		
EIA	Electronic Industries Alliance		
F-RAM	Ferroelectric Random Access Memory		
I/O	Input/Output		
JEDEC	Joint Electron Devices Engineering Council		
JESD	JEDEC Standards		
LSB	Least Significant Bit		
MSB	Most Significant Bit		
RoHS	Restriction of Hazardous Substances		
SPI	Serial Peripheral Interface		
SOIC	Small Outline Integrated Circuit		

### **Document Conventions**

#### **Units of Measure**

Symbol	Unit of Measure		
°C	degree Celsius		
Hz	hertz		
kHz	kilohertz		
kΩ	kilohm		
Mbit	megabit		
MHz	megahertz		
μΑ	microampere		
μF	microfarad		
μS	microsecond		
mA	milliampere		
ms	millisecond		
ns	nanosecond		
Ω	ohm		
%	percent		
pF	picofarad		
V	volt		
W	watt		



## **Document History Page**

Document Title: FM25V05	, 512-Kbit (64 K × 8) Serial (SPI) F-RAM
Decument Number 001.0	

Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
**	3912930	GVCH	02/25/2013	New spec
*A	3994285	GVCH	05/14/2013	Removed FM25VN05 part related information Added Appendix A - Errata for FM25V05
*B	4045438	GVCH	06/30/2013	All errata items are fixed and the errata is removed.
*C	4227764	GVCH	01/23/2014	Converted to Cypress standard format Updated Maximum Ratings: - Removed Moisture Sensitivity Level (MSL) - Added junction temperature and latch up current Updated Data Retention and Endurance: - Added data retention value at 65 °C and 75 °C temperature Added Thermal Resistance: Removed Package Marking Scheme (top mark) Removed Ramtron revision history Completing Sunset Review.
*D	4563141	GVCH	11/06/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end.
*E	4875900	ZSK / PSR	08/07/2015	Updated Maximum Ratings: Removed "Maximum junction temperature". Added "Maximum accumulated storage time". Added "Ambient temperature with power applied". Updated Package Diagram: spec 51-85066 – Changed revision from *F to *G. Updated to new template.
*F	5033012	GVCH	12/02/2015	Updated Status Register and Write Protection: Updated Table 3: Fixed typo error (Replaced "Bit 7" with "Bit 6" in "Bit" column). Updated Package Diagram: spec 51-85066 – Changed revision from *G to *H.



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